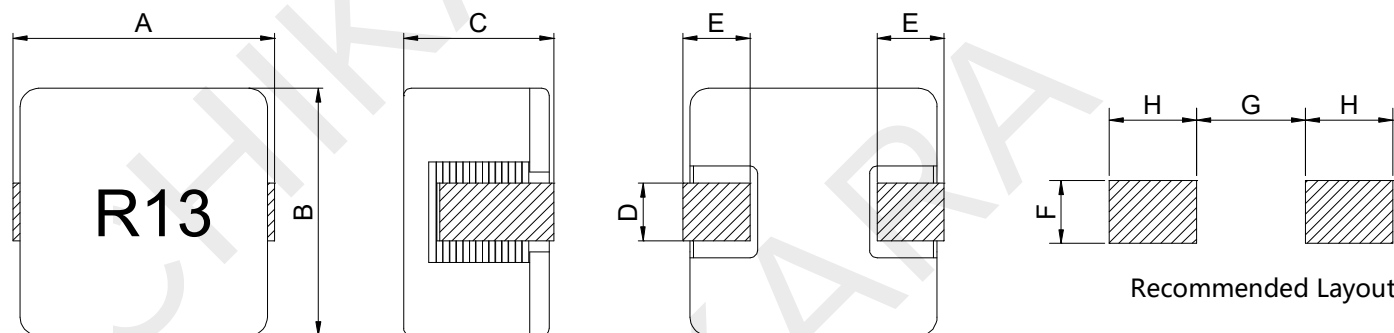


Features

- Magnetically shielded construction, Flat wire
- Storage temperature range:-55°C to + 125°C
- Operating temperature range:-55°C to + 125°C
(including coil's self-temperature rise)
- Moisture sensitivity level:1
- Packaging:1500pcs. Per 13-inch reel
- RoHs&Halogen-free compliant



Mechanical Dimension(Unit:mm)



A	B	C	D	E	F	G	H
7.0±0.3	6.9±0.3	3.0±0.3	1.2±0.3	1.8±0.3	2.2	2.4	2.7

Part Number Description

SP17 - 070030 R13 M
① ② ③ ④

①	Type
②	Dimensions
③	Inductance value
④	Tolerance code

Electrical Schematic



Electrical Characteristic

Part Number	Inductance L0(μH)	DCR (mΩ)	SRF (MHz)Typ.	Isat (A)Typ.	Irms (A)Typ.
SP17-070030R13M	0.13±20%	0.91±10%	400	48	22
SP17-070030R24M	0.24±20%	1.8±10%	220	40	18
SP17-070030R52M	0.52±20%	3.7±10%	140	20	14
SP17-070030R95M	0.95±20%	6.2±10%	90	14	11
SP17-070030R12M	1.2±20%	8.6±10%	84	13	8.5
SP17-070030R15M	1.5±20%	12.7±10%	80	12	7.5
SP17-070030R20M	2.0±20%	14.2±10%	58	9	6.5

- Test frequency and voltage:100KHz,0.1Vrms.
- All test data referenced to 25°C ambient.
- Saturation current(Isat) will cause L0 to drop approximately 30%.
- Heat rated current(Irms) will cause the coil temperature rise approximately Δt of 40°C.
- Heat rated current (Irms) is tested on a typical PCB and apply a constant current in still air. The temperature rise is dependent on the application system condition including PCB PAD pattern, trace width and thickness and adjacent components etc. It' s suggested to verify the temperature rise of the component under the real operation application conditions.

Soldering Specification

- Reflow profile for SMT components



- Classification of peak package body temperature (Tp)

	Package Thickness	Package Volume		
		<350mm ³	350~2000mm ³	>2000mm ³
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.